

TEST SEARCH

application # 10/775,232

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	45	sony.as. and barrier and resist and board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/08 13:03
S1	4	((("5,460,767") or ("6531,663") or ("6,049,122") or ("4,823,217"))). PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/31 18:01
S2	11	((("6,143,991") or ("5,925,445") or ("5,646,068") or ("5,640,308") or ("4,580,193") or ("6,038,132") or ("6,087,676") or ("5,52,567") or ("5,460,767") or ("6,531,663") or ("6,049,122") or ("4,823,217"))). PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/31 18:02
S3	48	((("6199273") or ("5642261") or ("5760469") or ("4336551") or ("5767528") or ("5841194") or ("5893508") or ("6013953") or ("6038135") or ("6186389") or ("6218630") or ("6218630") or ("6246117") or ("4322777") or ("5010448") or ("5418471") or ("5478009") or ("5484963") or ("5491364") or ("5512786") or ("5545589") or ("5594275") or ("5620928") or ("5672965") or ("5699612") or ("5708567") or ("5726493") or ("5729432") or ("5732465") or ("5736789") or ("5736790") or ("5784264") or ("5783870") or ("5789716") or ("5803340") or ("5828128") or ("5838061") or ("5849609") or ("5854741") or ("5866948") or ("5878942") or ("5889333") or ("5891758") or ("5897334") or ("5898217") or ("5905633") or ("5908317") or ("5909055") or ("5912505") or ("5915169").pn.))). PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/31 18:04
S4	3	((("6833509") or ("6498306") or ("6420658"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/31 18:08
S5	14096	((substrate or board or carrier) with (pad\$1 or land\$1) with (terminal\$1 or electrode\$1)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:04

S6	4443	((substrate or board or carrier) with (pad\$1 or land\$1) with (terminal\$1 or electrode\$1)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:09
S7	34	((substrate or board or carrier) with (pad\$1 or land\$1) with (terminal\$1 or electrode\$1) with (mask or resist or protect\$4 adj coating) with (trench\$2 or channel\$1 or groove\$1 or slot\$1)). ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:49
S8	5	((substrate or board or carrier) with (pad\$1 or land\$1) with (terminal\$1 or electrode\$1) with (mask or resist or protect\$4 adj coating) with (trench\$2 or channel\$1 or groove\$1 or slot\$1)). clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:07
S9	8014	((substrate or board or carrier) with (mask or resist or protect\$4 adj coating) with (trench\$2 or channel\$1 or groove\$1 or slot\$1)). ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:09
S10	2923	((substrate or board or carrier) with (mask or resist or protect\$4 adj coating) with (trench\$2 or channel\$1 or groove\$1 or slot\$1)). clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:06
S11	34	S7 not S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:07
S12	1431	S5 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:10
S13	3	S9 and S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:10

S14	1123	S12 and (chip or ic or semiconductor adj device or die or package or integrated adj circuit\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:12
S15	484	S14 and edge	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:42
S16	7	(substrate or board or carrier) with (pad\$1 or land\$1) with (terminal\$1 or electrode\$1) with (mask or resist or protect\$4 adj coating) with (trench\$2 or channel\$1 or groove\$1 or slot\$1) with (edge\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:50
S17	0	(substrate or board or carrier) with (pad\$1 or land\$1 or terminal\$1 or electrode\$1) with (mask or resist or protective adj coating) with (edge) with (solder adj dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:53
S18	2	(substrate or board or carrier) same (pad\$1 or land\$1 or terminal\$1 or electrode\$1) same (mask or resist or protective adj coating) with (edge) same (solder adj dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 11:53
S19	108	(substrate or board or carrier) and (pad\$1 or land\$1 or terminal\$1 or electrode\$1) and (mask or resist or protective adj coating) and (edge) and (solder adj dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 12:20
S20	11	((("6608,375") or ("6787,923") or ("6,911173") or ("20010010947") or ("20020171177") or ("20030043360") or ("20030052419") or ("20030151167") or ("20040014255") or ("20040005770") or ("20040080027") or ("20040142058") or ("20040165362"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/01/01 11:59
S21	2	("5744084" "6479887").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/01 12:02
S22	0	("6787923").URPN.	USPAT	OR	ON	2006/01/01 12:02

S23	4440657	(substrate or board or carrier or pcb or pwb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 12:18
S24	92214	S23 and ((pad\$1 or land\$1 or terminal\$1 or electrode\$1) with (edge))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 12:22
S25	26430	S24 and (mask or resist or protective adj coating or solder adj dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 12:21
S26	17135	S25 and (trench\$2 or channel\$1 or groove\$1 or slot\$1 or slit\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 12:21
S27	10314	S26 and parallel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 12:21
S28	174	S26 and ((pad\$1 or land\$1) with (terminal\$1 or electrode\$1) with (parallel))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 12:32
S29	1434	S8 or S11 or S13 or S14 or S15 or S16 or S19 or S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 12:33
S30	2205	(174/260).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/01 12:34

S31	2152	S30 not S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 12:34
S32	1929	(174/260).CCLS.	US-PGPUB; USPAT	OR	OFF	2006/01/01 16:06
S33	1876	S32 not S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 14:20
S34	7	("4656605" "5572457" "6208546" "6222739" "6492714" "6725414" "6784526").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/01 12:51
S35	0	("6850414").URPN.	USPAT	OR	ON	2006/01/01 12:51
S36	5	("5460767" "5737191" "5859475" "5907190" "6365979").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/01 12:57
S37	0	("6617524").URPN.	USPAT	OR	ON	2006/01/01 12:57
S38	3	("4722470" "5060844" "5147084").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/01 14:04
S39	24	("5493075").URPN.	USPAT	OR	ON	2006/01/01 14:05
S40	11599	((174/255) or (174/260) or (174/261) or (174/250) or (174/254) or (174/267) or (174/268) or (361/777) or (361/760) or (361/746) or (257/778) or (257/667) or (257/671)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/01 14:18
S41	0	("36and((damordamming)with(sol derorreflow))").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/01 14:19
S42	143	S40 and ((dam or damming) with (solder or reflow))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 14:19

S43	96	S42 not (S32 or S29)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 14:38
S44	6	("5,930,889") or ("20040040742") or ("6,927,347") or ("5,075,965") or ("5,930,889") or ("6,870,248") or ("6,933, 617")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/01/01 14:25
S45	873	(361/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/01 14:38
S46	704	S45 not (S42 or S32 or S29)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 15:16
S47	555	(257/667).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/01 15:16
S48	532	S47 not (S45 or S42 or S32 or S29)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 16:03
S49	1	("6600217").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/01/01 15:45
S50	2	("5920116" "6506257").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/01 15:46
S51	0	("6600217").URPN.	USPAT	OR	ON	2006/01/01 15:46
S52	150	(257/671).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/01 16:03

S53	142	S52 not (S47 or S45 or S42 or S32 or S29)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 16:07
S54	268	S31 not (S52 or S47 or S45 or S42 or S32 or S29)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 16:11
S55	2131	(174/261).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/01 16:10
S56	1367	S55 not (S31 or S52 or S47 or S45 or S42 or S32 or S29)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 16:52
S57	6158	((174/255) or (174/260) or (174/261) or (361/777) or (257/667) or (257/671)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/01 16:53
S58	1843	(361/760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/01 16:53
S59	1183	S58 not S57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 17:09
S60	1189	(174/250).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/01 17:09

S61	0	S59 not (S58 or S57)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 17:09
S62	710	S60 not (S58 or S57)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 17:22
S63	1104	(174/254).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/01 17:22
S64	687	S63 not (S60 or S58 or S57)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 17:37
S65	875	((174/267) or (174/268)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/01 17:37
S66	382	S65 not (S63 or S60 or S58 or S57)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/01 17:41
S67	6	((module near3 circuit) with (barrier) with (isolate or isolation) with (semiconductor or chip or die or IC)).ti,ab,clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 17:00
S68	6	((module near3 circuit) with (barrier) with (isolate or isolation) with (semiconductor or chip or die or IC))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 17:00

S69	199706	Takahashi.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 17:04
S70	841	S69 and (pad\$1) and (terminal\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 17:05
S71	641	S70 and (semiconductor or chip or die or IC)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 17:06
S72	159	S70 and (barrier or stopper or dam or damming)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 17:16
S73	244	S71 and (resist or mask or protective adj coating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 17:17
S74	155	S73 not S72	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 17:20
S75	59	(board with resist with barrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 15:21
S76	3	("4088828" "4220810" "4389771").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 13:48
S77	10	("4767892").URPN.	USPAT	OR	ON	2006/01/06 13:49

S78	14	("3567844" "3610811" "3777221" "4303291" "4326239" "4413309" "4584039" "4590539" "4638116" "4694121" "4706167" "4728022" "4766268" "4767892").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 13:52
S79	10	("4859808").URPN.	USPAT	OR	ON	2006/01/06 13:54
S80	6926	pfu.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 14:33
S81	1	S80 and (barrier with resist)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 14:34
S82	32	((board or substrate) with (resist or mask) with (barrier or dam or damming) with (channel or trench)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 14:37
S83	100	((board or substrate) with (resist or mask) with (barrier or dam or damming) with (channel or trench)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 14:35
S84	2	S82 and S83	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 14:35
S85	2	(board or substrate) with (solder adj resist or solder adj mask) with (barrier or dam or damming) with (channel or trench) with (solder or reflow)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 15:10
S86	12	(board or substrate) same (solder adj resist or solder adj mask) same (barrier or dam or damming) same (channel or trench) same (solder or reflow)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 16:45

S87	503	(board or substrate) and (solder adj resist or solder adj mask) and (barrier or dam or damming) and (channel or trench or groove) and (solder or reflow)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 14:51
S88	1	("6853089").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/01/06 14:51
S89	9	("20010026959" "20020084518" "20020125557" "20020149102" "20020168798" "20030042621" "5336931" "6200121" "6448507").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 14:54
S90	0	("6853089").URPN.	USPAT	OR	ON	2006/01/06 14:54
S91	130	S82 or S83	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 15:07
S92	127	S91 not S87	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 15:08
S93	6	(board or substrate) with (solder adj resist or solder adj mask) with (solder near3 bridg\$4).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 15:16
S94	26	(board or substrate) with (solder adj resist or solder adj mask) with (solder near3 bridg\$4).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 15:11
S95	117	(board or substrate) with (solder adj resist or solder adj mask) with (solder near3 bridg\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 15:16
S96	79	S95 not (S94 or S93 or S92 or S87 or S86 or S85 or S75)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 15:21

S97	361	(board same resist same barrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 15:21
S98	296	S97 not (S95 or S94 or S93 or S92 or S87 or S86 or S85 or S75)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 17:11
S99	2	("4489364" "4546413").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 15:32
S10 0	1	("5233503").URPN.	USPAT	OR	ON	2006/01/06 15:32
S10 1	12	("3405224" "4554732" "4766268" "4779339" "4847003" "4859808" "4931323" "4959751" "5004640" "5041901" "5113239").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 15:34
S10 2	2	("5281772").URPN.	USPAT	OR	ON	2006/01/06 15:34
S10 3	5	((("6420658") or ("6498306") or ("6833509"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/06 15:54
S10 4	12	("4580193" "4823217" "5460767" "5552567" "5640308" "5646068" "5925445" "6038132" "6049122" "6087676" "6143991" "6531663").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 15:56
S10 5	2	("4188714" "4432027").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 16:01
S10 6	30	("4823217").URPN.	USPAT	OR	ON	2006/01/06 16:01
S10 7	4	("4017889" "4929284" "5164342" "5637261").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 16:09
S10 8	1	("6531663").URPN.	USPAT	OR	ON	2006/01/06 16:09

S10 9	10	("3780352" "5245750" "5279711" "5345365" "5432679" "5438478" "5467253" "5523920" "5790377" "5864946").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 16:11
S11 0	12	("6143991").URPN.	USPAT	OR	ON	2006/01/06 16:12
S11 1	12	("6143991").URPN.	USPAT	OR	ON	2006/01/06 16:12
S11 2	21	("3561107" "3704164" "3811183" "4610910" "4847003" "4925723" "5153051" "5493075" "5512712" "5545465" "5550325" "5576869" "5578874" "5608262" "5656862" "5672913" "5674595" "5703406" "5744224").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 16:14
S11 3	8	("5925445").URPN.	USPAT	OR	ON	2006/01/06 16:15
S11 4	0	("6833509").URPN.	USPAT	OR	ON	2006/01/06 16:15
S11 5	8	("4580193" "5552567" "5640308" "5646068" "5925445" "6038132" "6087676" "6143991").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 16:16
S11 6	10	("3780352" "5245750" "5279711" "5345365" "5432679" "5438478" "5467253" "5523920" "5790377" "5864946").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 16:16
S11 7	12	("6143991").URPN.	USPAT	OR	ON	2006/01/06 16:17
S11 8	0	("6498306").URPN.	USPAT	OR	ON	2006/01/06 16:17
S11 9	8	("4580193" "5552567" "5640308" "5646068" "5925445" "6038132" "6087676" "6143991").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 16:17
S12 0	653	((solder adj resist or solder adj mask) same (pad or land or electrode or terminal)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 16:46

S12 1	2343	((solder adj resist or solder adj mask) same (pad or land or electrode or terminal)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 17:09
S12 2	275	S120 and S121	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 17:00
S12 3	2	("4230793" "4884337").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 16:57
S12 4	11	("5402314").URPN.	USPAT	OR	ON	2006/01/06 16:58
S12 5	2721	S120 or S121	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 17:00
S12 6	11	S125 and (solder adj stop\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 17:01
S12 7	10	("3458925" "4273859" "4450188" "4661192" "4661375" "4729165" "5048747" "5092034" "5135155").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 17:03
S12 8	20	("5281684").URPN.	USPAT	OR	ON	2006/01/06 17:04
S12 9	20	("5281684").URPN.	USPAT	OR	ON	2006/01/06 17:04
S13 0	6516	((solder adj resist or solder adj mask) same (pad or land or electrode or terminal))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 17:10
S13 1	675	S130 and barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 17:10

S13 2	384	S131 not (S122 or S97 or S95 or S94 or S93 or S92 or S87 or S86 or S85 or S75)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 18:01
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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S13	216931	(board or substrate) with (insulating adj film or resist or mask or potective adj coating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/07 20:10
S22	68	S13 and ((under\$1fill or under adj fill) with (viscosity))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 13:46
S34	83178	oki.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 18:44
S35	71	S34 and (solder adj resist or solder adj mask) and (board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 18:52
S36	21394	H05K001/02.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 18:52
S37	35708	H05K003/34.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 18:52
S38	55786	S36 or S37	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 18:52
S39	1454	S38 and (solder adj resist or solder adj mask) and (board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:28

S40	43	S38 and (solder adj dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:28
S41	13	S39 and S40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 18:54
S42	9	S38 and (barrier with resist)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:29
S43	1028	S38 and (solder near3 bridg\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:30
S44	103	S39 and S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:10
S45	97	S44 not (S42 or S41 or S35)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:27
S46	0	S39 and ((mask or resis) with (moat))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:26
S47	3	S39 and ((mask or resis) with (barrier))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:26

S48	2102	((228/180.21) or (228/180.22)). CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/07 19:27
S49	798	b23k001/14.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:28
S50	2898	S48 or S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:28
S51	246	S50 and (solder adj resist or solder adj mask) and (board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:28
S52	5	S51 and (solder adj dam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:28
S53	15	S50 and (barrier with resist)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:33
S54	159	S50 and (solder near3 bridg\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:31
S55	14	S54 and (S53 or S52 or S47 or S45 or S42 or S41)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:33

S56	59	S50 and (dam or damming or moat)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:35
S57	8	S56 and (S54 or S53 or S52 or S47 or S45 or S42 or S41)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:36
S58	5	S50 and ((mask or resist) with (channel or trench))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:36
S59	0	S58 and (S56 or S54 or S53 or S52 or S47 or S45 or S42 or S41)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:37
S60	22	S38 and ((mask or resist) with (channel or trench))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:42
S61	4	S60 and (S58 or S56 or S54 or S53 or S52 or S47 or S45 or S42 or S41)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:38
S62	61	S38 and ((mask or resist) with (groove))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:37
S63	2	S62 and (S60 or S58 or S56 or S54 or S53 or S52 or S47 or S45 or S42 or S41)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:40

S64	58328	S38 or S50	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:39
S65	19584	S64 and (land or pad or electrode or terminal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:40
S66	154	S65 and ((land or pad or electrode or terminal) with (barrier))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:40
S67	13	S66 and (S62 or S60 or S58 or S56 or S54 or S53 or S52 or S47 or S45 or S42 or S41)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:43
S68	403	S64 and ((mask or resist or insulat\$4) with (channel or trench or groove or slot))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:51
S69	92	S68 and (S66 or S62 or S60 or S58 or S56 or S54 or S53 or S52 or S47 or S45 or S42 or S41)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:51
S70	7	S64 and ((mask or resist or insulat\$4) with (solder adj adhesion))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:53
S71	2	S70 and (S68 or S66 or S62 or S60 or S58 or S56 or S54 or S53 or S52 or S47 or S45 or S42 or S41)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:55

S72	231	S64 and ((solder near3 stop\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:53
S73	14	S72 and (S70 or S68 or S66 or S62 or S60 or S58 or S56 or S54 or S53 or S52 or S47 or S45 or S42 or S41)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 19:56
S74	386	S48 and (S72 or S70 or S68 or S66 or S62 or S60 or S58 or S56 or S54 or S53 or S52 or S47 or S45 or S42 or S41)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/07 20:02
S75	13	pfu.as. and Tatsuhiko.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/08 10:32
S76	6927	pfu.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/08 10:32
S77	1	S76 and barrier and resist	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/08 10:33
S78	16	hitachi.as. and (solder adj resist) and (solder adj bridge)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/08 10:55